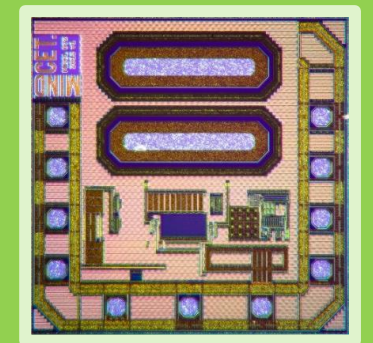
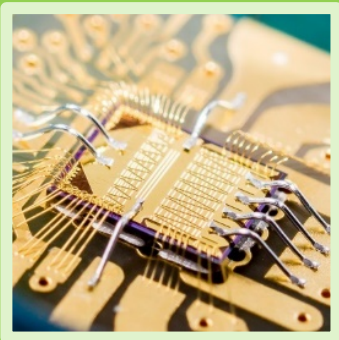


Unleashing GaN with High-Performance Gate Driving

Dr. Mike Wens

WE Meet @ Digital Days / 27.04.2021

MINDCET.
Custom
Integrated Power
Management
Solutions



Contents

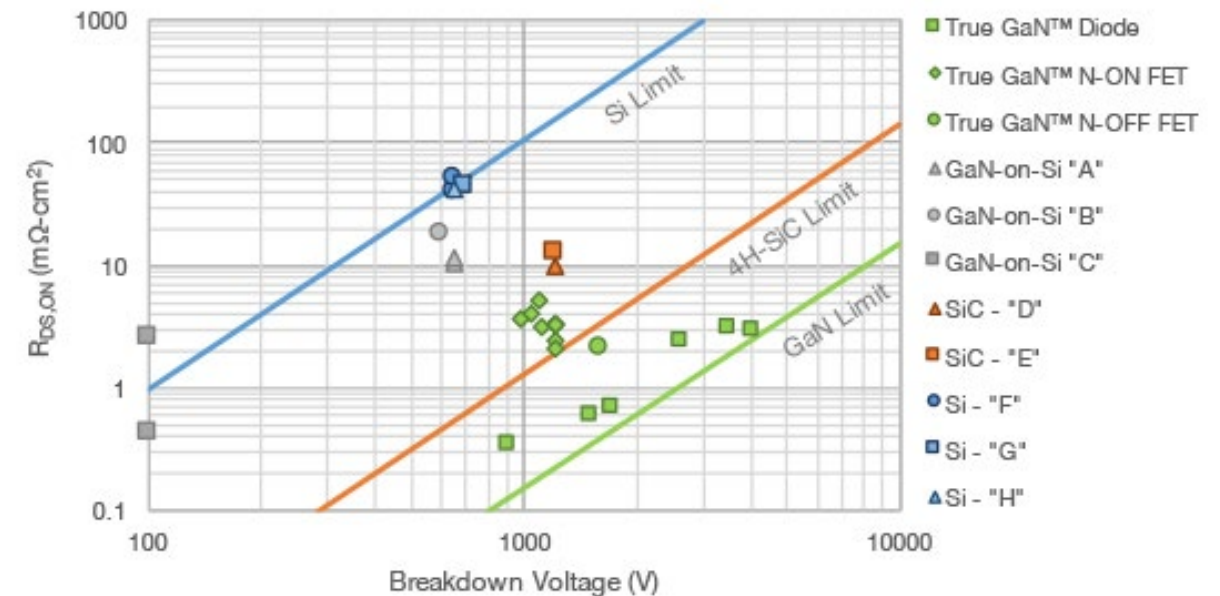


- Advantages of GaN
- Challenges of Driving GaN
- Our Answer: High-Speed GaN Gate-Driver
- MDC901 Evaluation Kit (EVK)
- Applications
- Thermal Performance
- Conclusions

Advantages of GaN

Compared to Silicon MOSFETs

- Faster switching transitions
- Improved $R_{ds(on)} \times \text{GateCharge}$
- Lower C_{oss} , C_{iss} , C_{rss}
- No reverse recovery
- Higher temperature capability



⇒ Theoretically enables higher SMPS efficiencies

⇒ But how can we enable this?

Source : nexgen powersystems

Challenges of Driving GaN

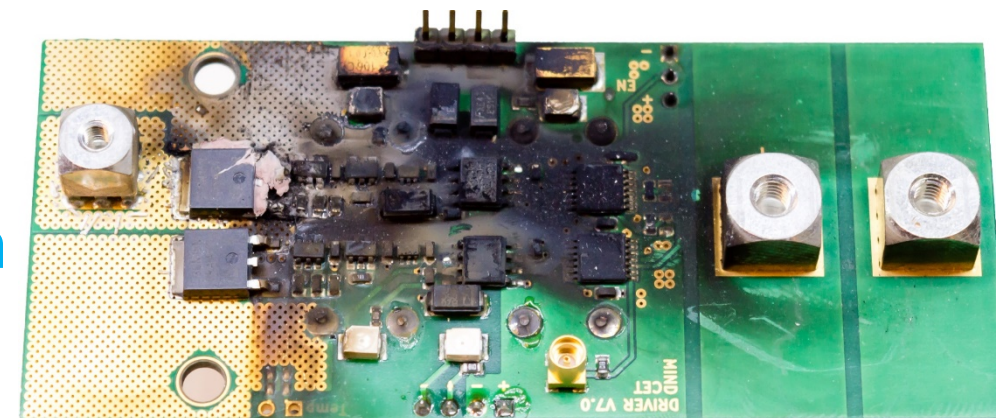
What not to do

A GaN HEMT is NO MOSFET:

- Lower and tighter controlled gate turn-on voltage
- Lower threshold voltage (V_{th})
- Significantly faster Turn On and Off times
- Lower $C_{gate-source} / C_{drain-gate}$ ratio

⇒ An ideal recipe for expensive fireworks

⇒ Needs an optimized gate-drive approach

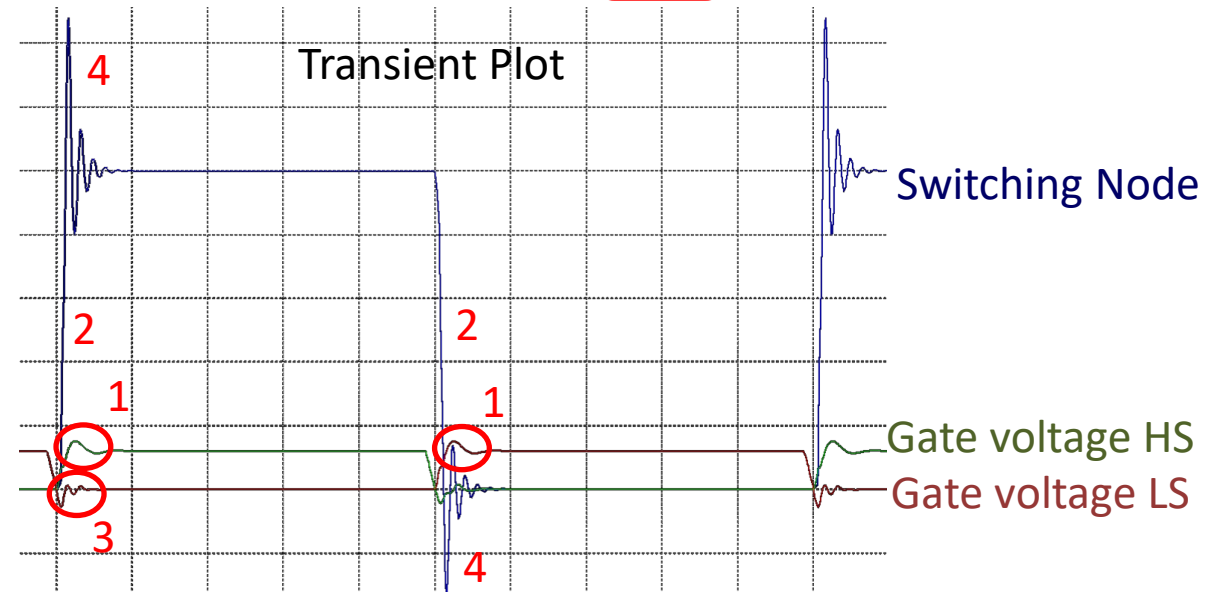
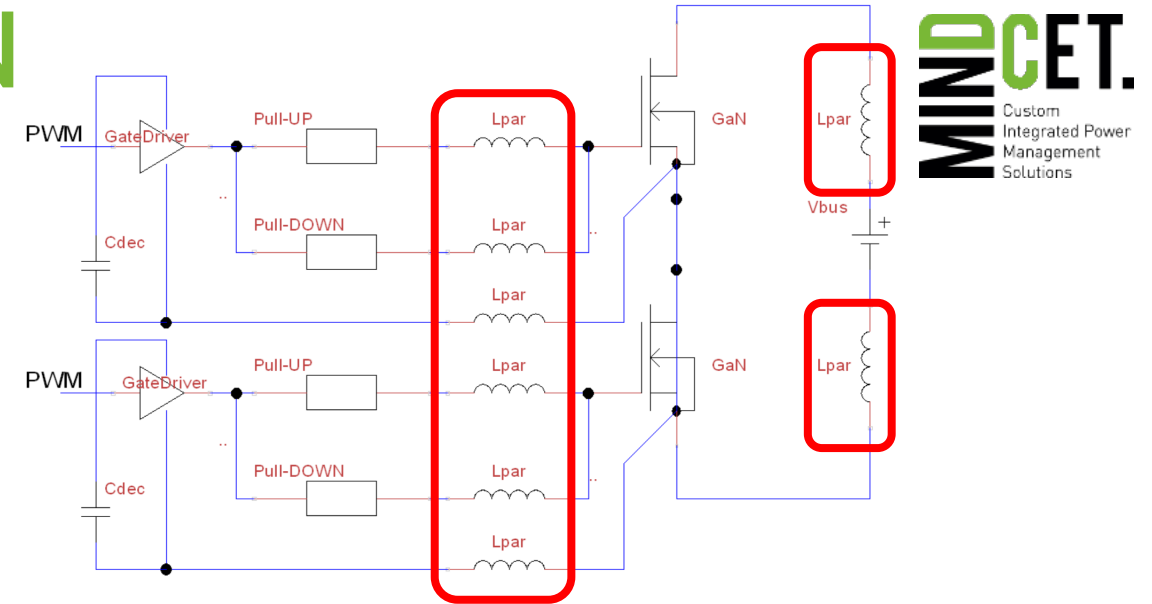


Challenges of Driving GaN

What to watch out for

On PCB level:

- **Gate-loop inductance**
 - Over-voltage stress on the gate 1
 - Limits transient speed 2
 - Parasitic turn-on 3
- **Supply inductance**
 - Ringing on switching node 4
 - Limits transient speed 2



Challenges of Driving GaN

What we need to watch out for

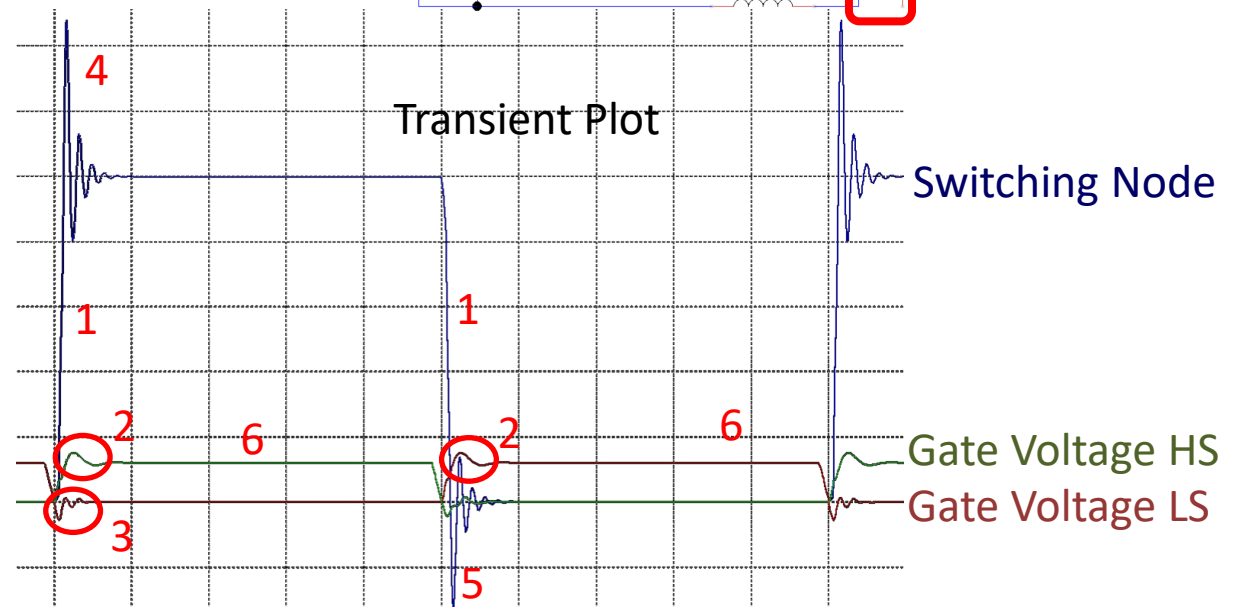
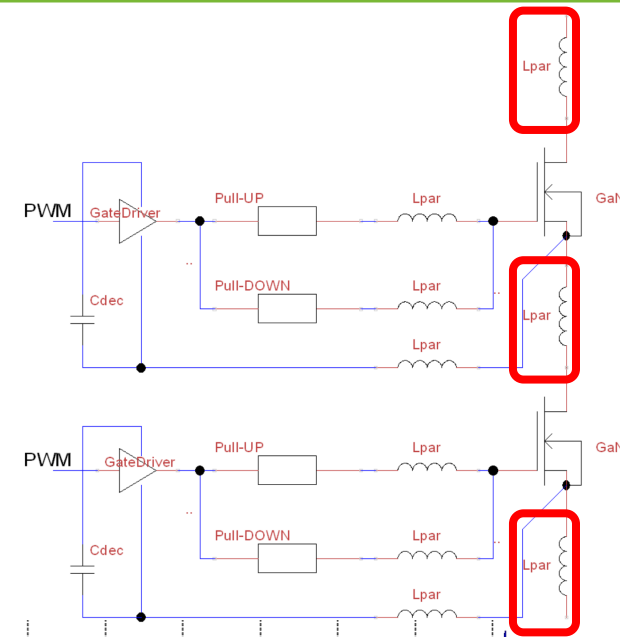
On PCB level:

- **Gate resistors**

- Regulates transient speed 1
- Keeps dissipation from the driver
- Dampens the gate LC 2
- Prevents parasitic turn-on 3

- **Drain-source inductance**

- Ringing on switching node 4
- Negative voltage on driver 5
- Over-charges bootstrap 6



Challenges of Driving GaN

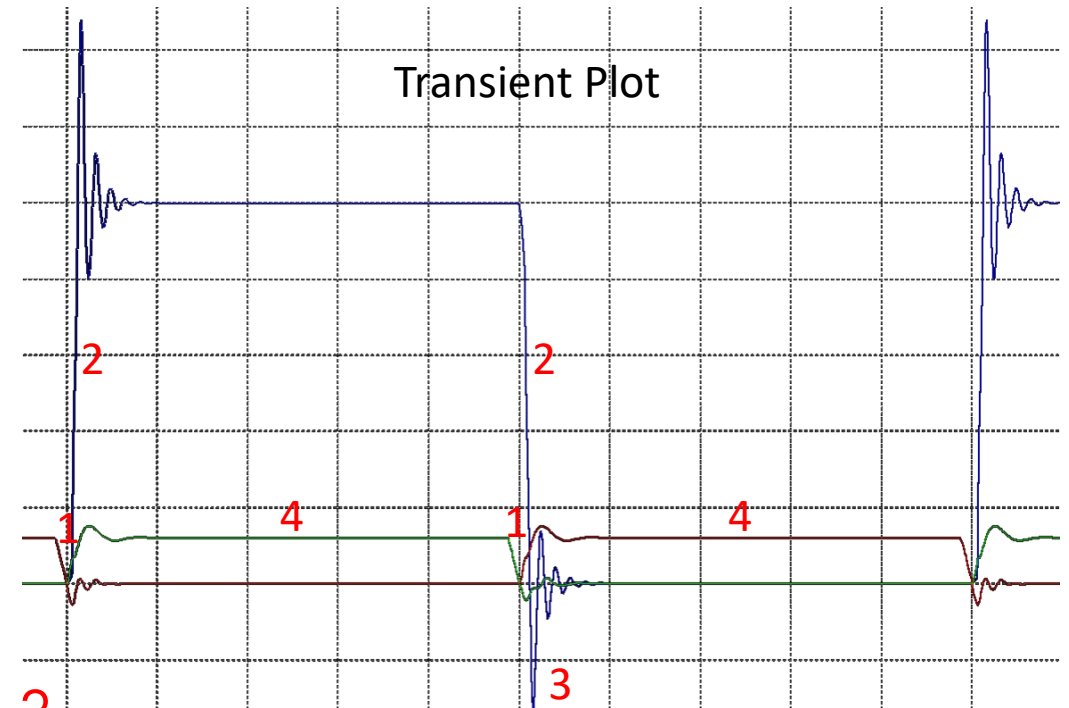
What the gate driver needs to overcome

- **Dead-time control 1**
 - Cross currents in GaN
 - Recirculation loss
- **LS/HS delay-matching 1**
 - Cross currents in GaN
- **dV/dt 2**
 - False gate commutation
 - Driver failure
- **Negative Source voltage = GND inductance 3**
 - False gate commutation
 - Driver failure
 - Bootstrap over-charging -> Gate-stress and breakdown 4

Switching Node

Gate Voltage LS

Gate Voltage HS



Our Answer: High-Speed GaN Gate-Driver

Key specifications MDC901

- 200V High and Low side
- 30ns propagation delay -> **Control loop stability**
- 1ns delay matching -> **Optimized dead-time**
- Slew rate 100V/ns compatible
 - > **High-speed switching**
- **10-A peak source, 17-A peak sink currents**
 - > **High-speed, no parasitic turn-on**
- **Up to -4V GaN source operation guaranteed**
 - > **No false-triggering of gate**
- -40 to 125°C ambient operation (-55° to 175°C junction temp possible)
 - > **High power density**



QFN56 7x7mm²

Our Answer: High-Speed GaN Gate-Driver

Device Features MDC901

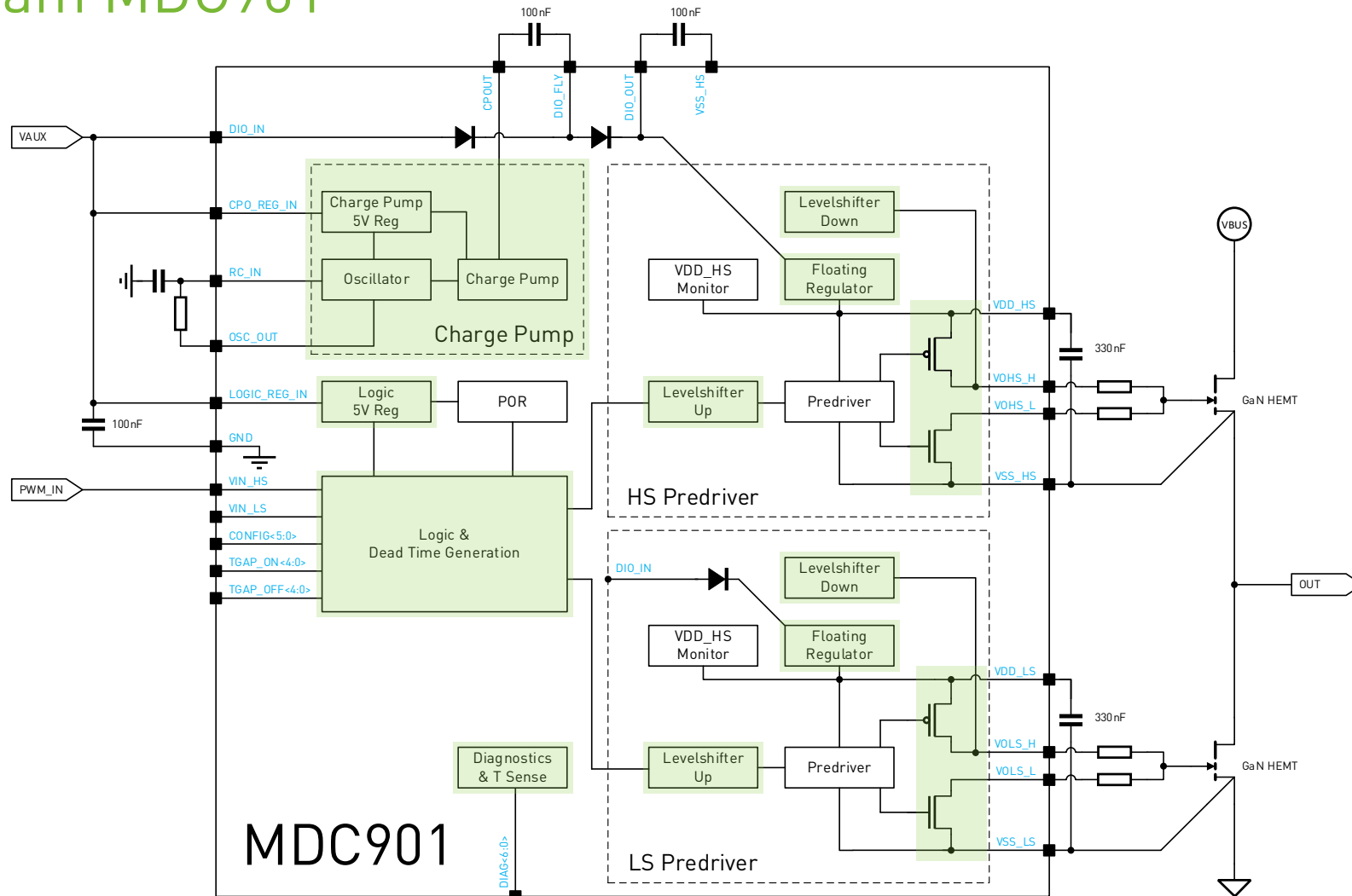
- Logic 5V as well as a floating & programmable HS/LS LDO for gate voltage 4-6.5V
 - > No gate-overcharge
- 100% duty cycle enabled by on-chip charge pump
 - > Low & high duty cycles
- Integrated Bootstrap diodes
 - > Gate power @ higher frequencies
- Automatic dead-time or programmable dead-time
 - > Maximal flexibility and reliability
- Internal temp sensor -> System monitoring
- UVLO -> Avoid insufficient gate-overdrive



QFN56 7x7mm²

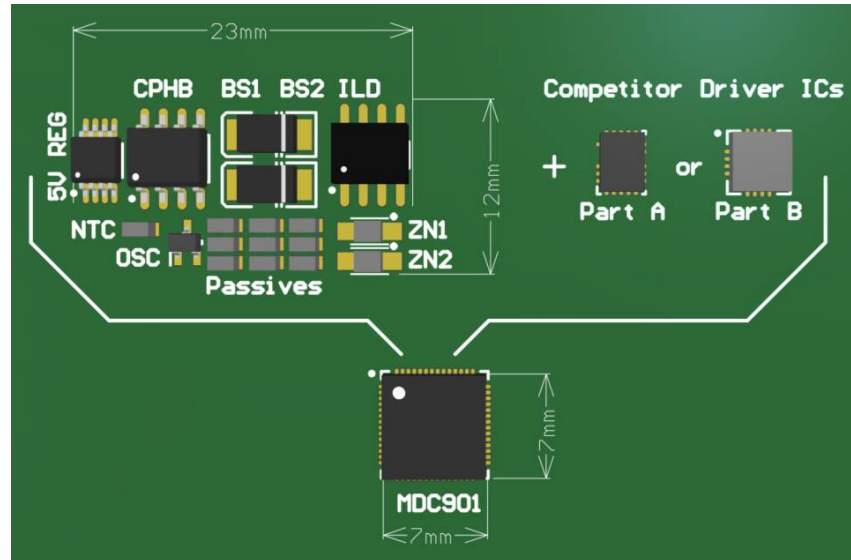
Our Answer: High-Speed GaN Gate-Driver

Block diagram MDC901

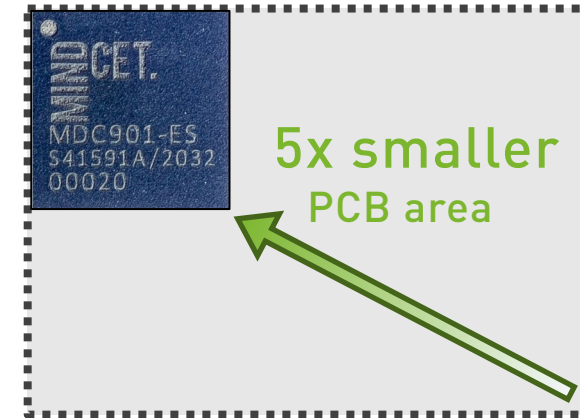


Our Answer: High-Speed GaN Gate-Driver

High level of integration for design ease & footprint reduction



Required external components for an equivalent competitor gate driver solution to the MDC901



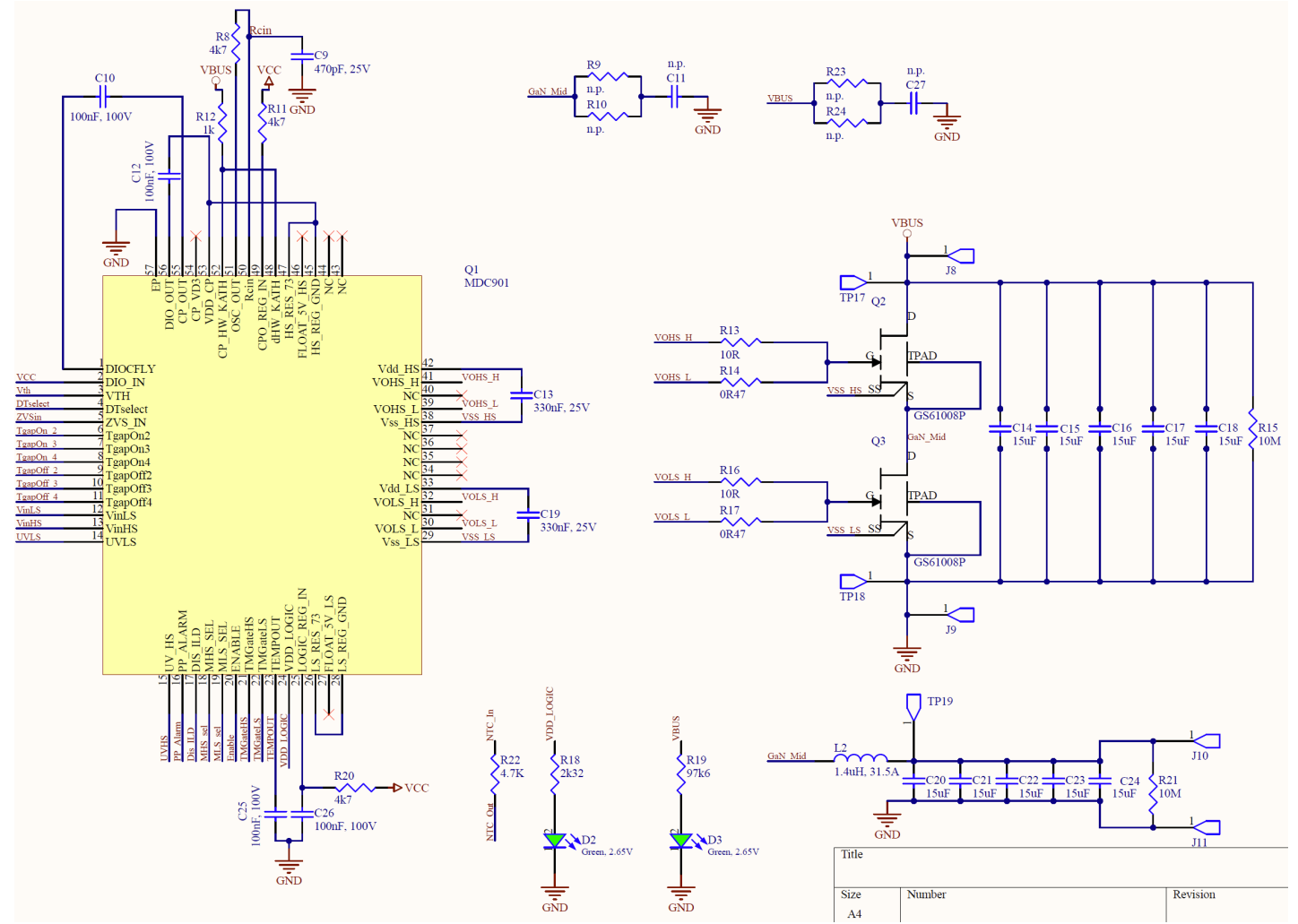
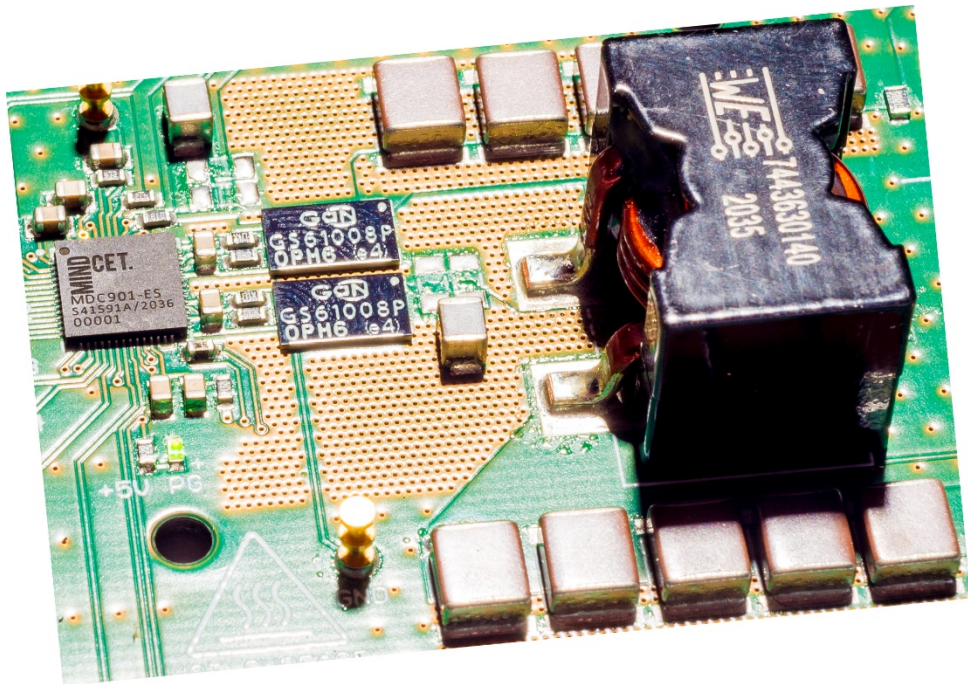
**shown to scale*

- Significant PCB footprint reduction → lowered costs
- Decreased design effort → faster time-to-market
- Increased system robustness through decreased part count

MDC901 provides decreased complexity with efficient & robust gate driving through a highly integrated gate drive IC

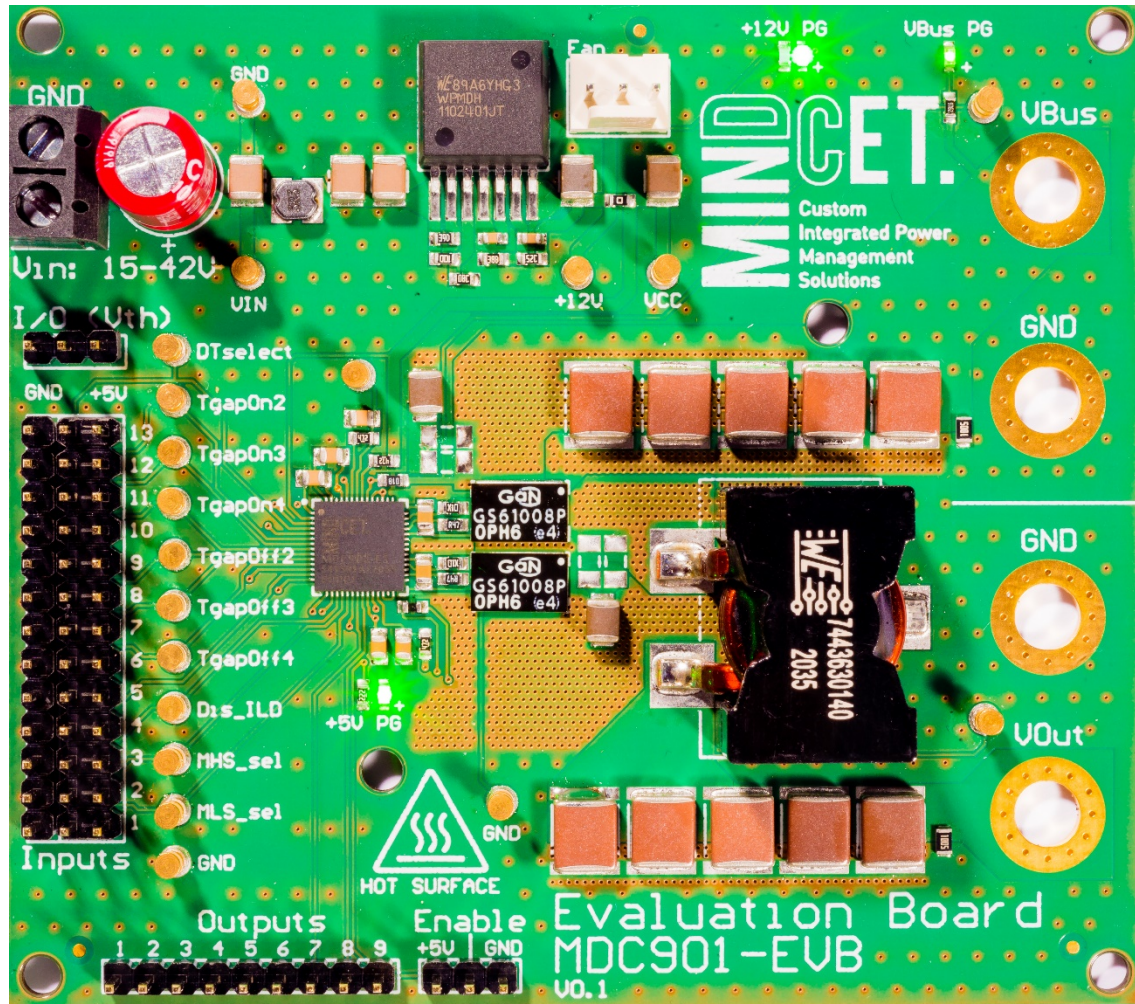
MDC901 Evaluation Kit

Main DC/DC circuit

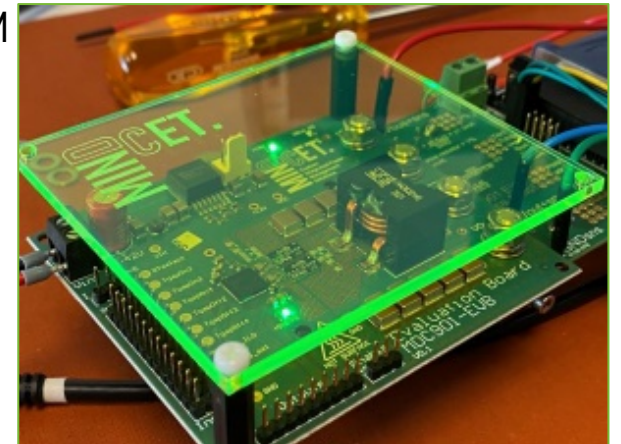


MDC901 Evaluation Kit

The hardware



- MDC901 200V GaN gate driver
- 100V HB HEMT featuring **GaN** GS61008P
- Featuring Würth Elektronik **WE** WÜRTH ELEKTRONIK components
- 20A/50V operation, 100V / 40A possible (thermal limitation)
- Thermistor close to GaN for temp monitoring
- Regulated 12V Fan supply
- All components mounted and materials provided:
 - Active heatsink + TIM
 - Plexi cover
 - Cables
 - Screw and bolts
 - Manual
 - Re-useable box

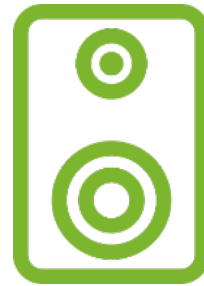


Applications

A versatile driver



Server & data center PoL



Audio class-D

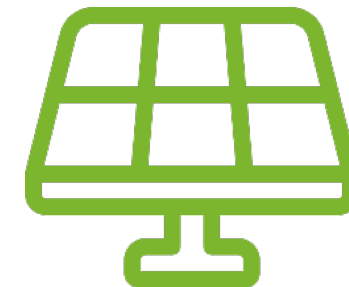


High-end eBikes & lightweight eMobility

High Performance
Consumer & Industrial
Applications



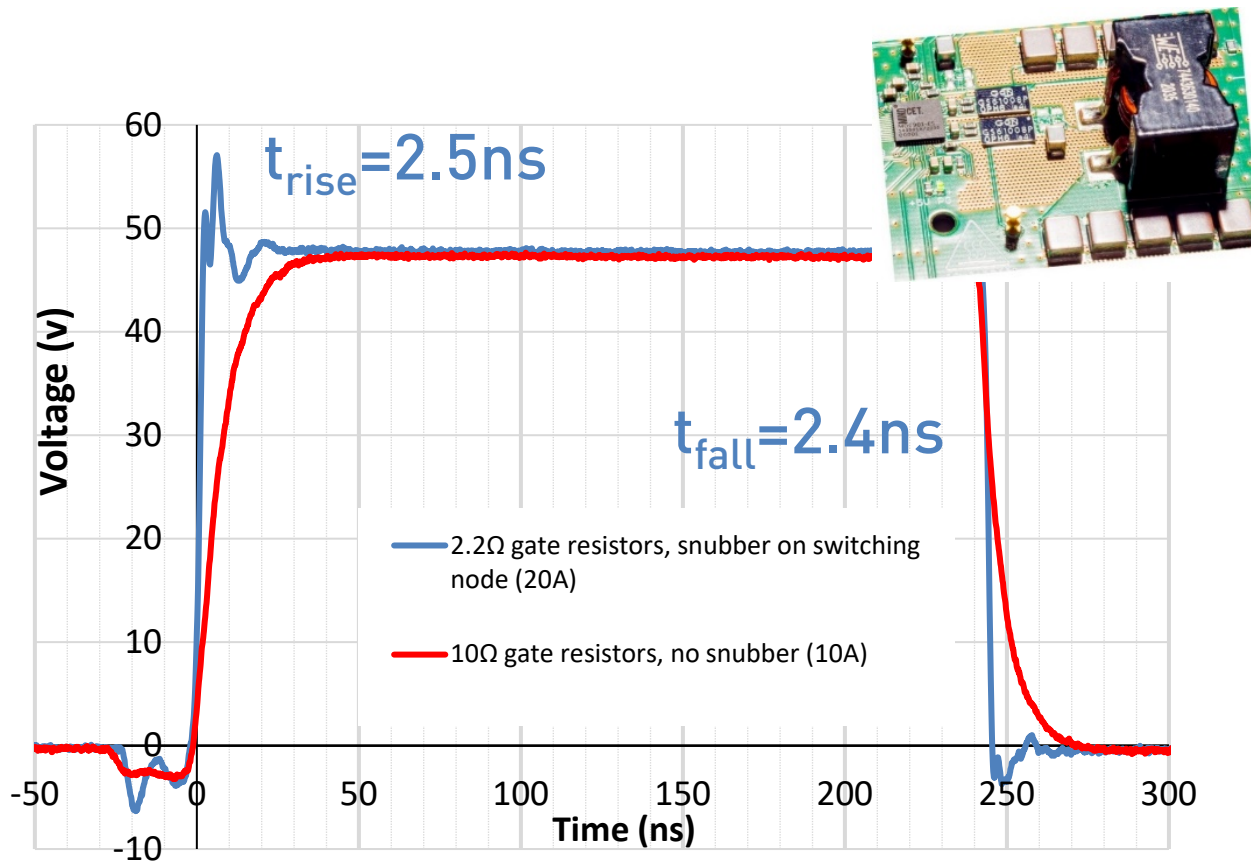
Battery-powered tools & devices
(e.g. power-tools, drones)



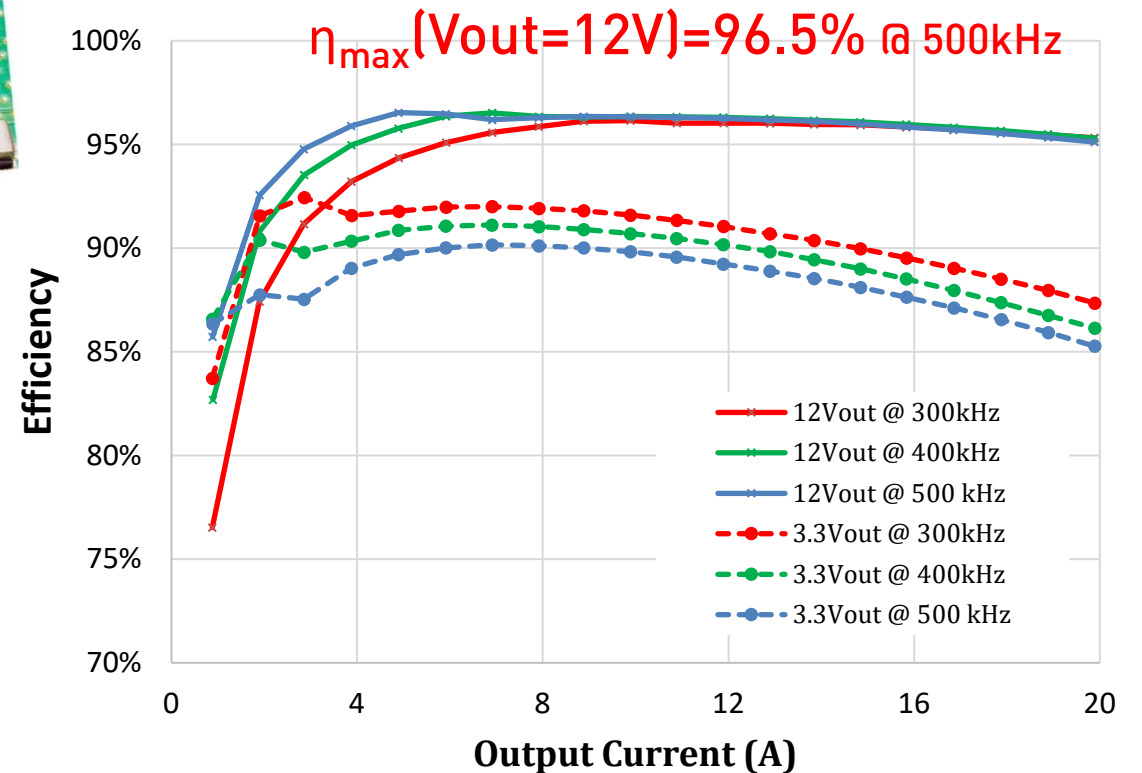
PV microinverter

Applications

Evaluation board performance in real-life: Buck DCDC



Tunable dv/dt

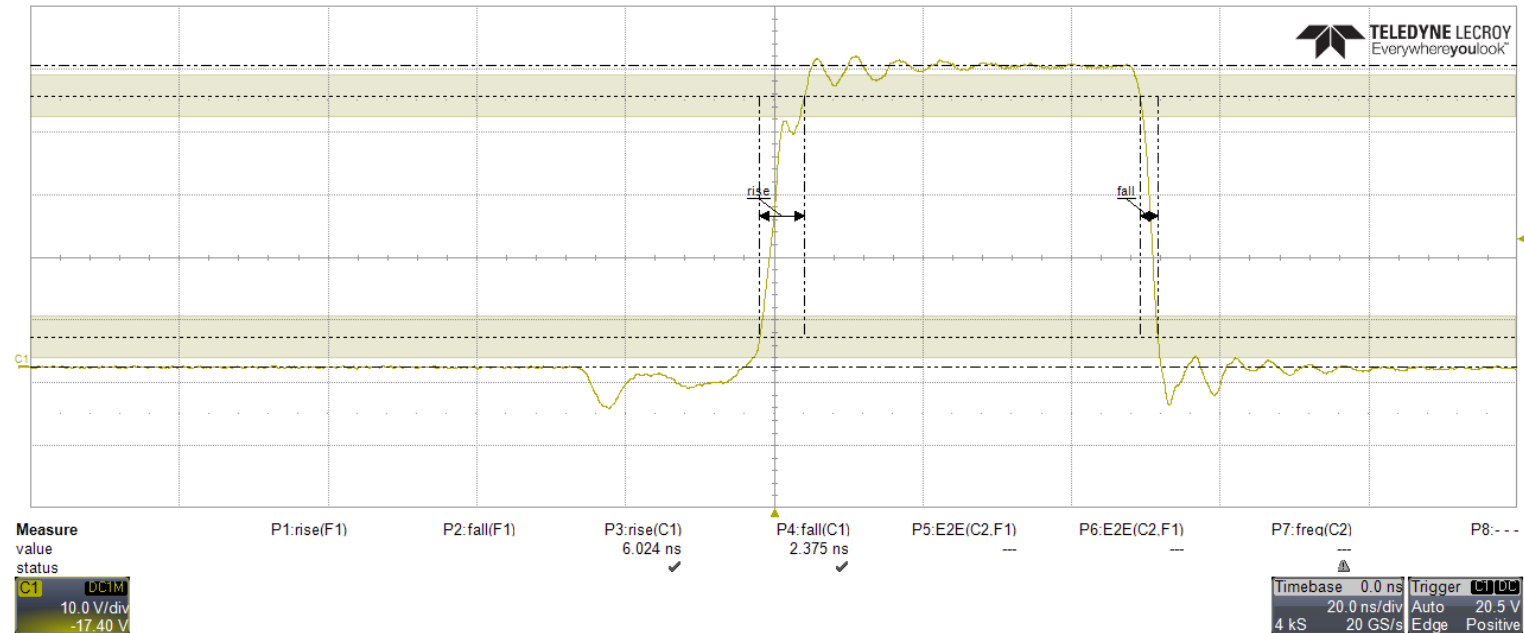
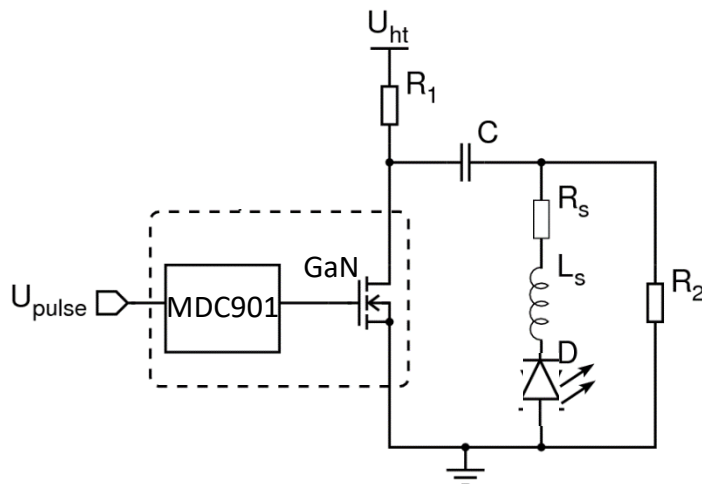
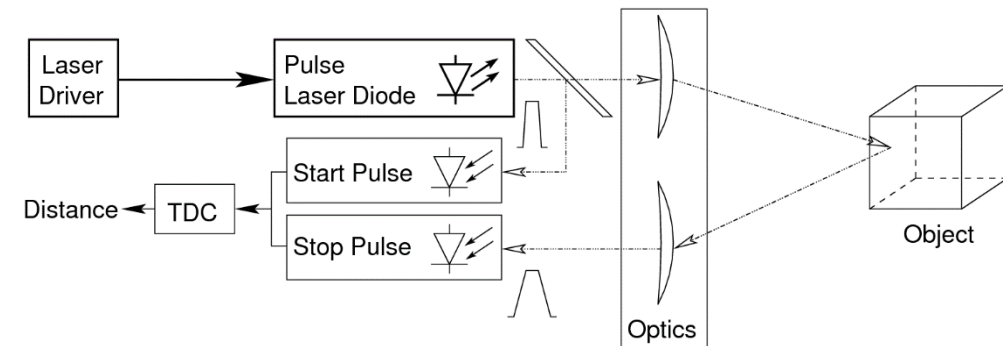


Efficiency curves for $V_{in}=48V$ to $V_{out}=12V$ or $3.3V$

Applications

LIDAR Laser Driver

- Short pulses with high current amplitude

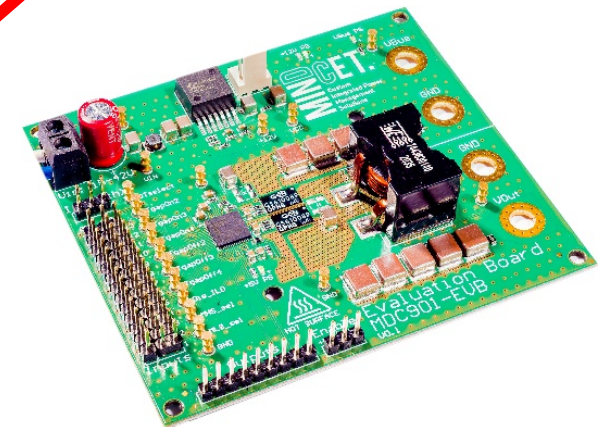


Applications

Class-D Audio Amplifier

- Low distortion:
 - Clean square-wave switching
 - Nano-second dead-time
- High efficiency
- High power density
- Deep modulation possible
 - Charge-pump

?

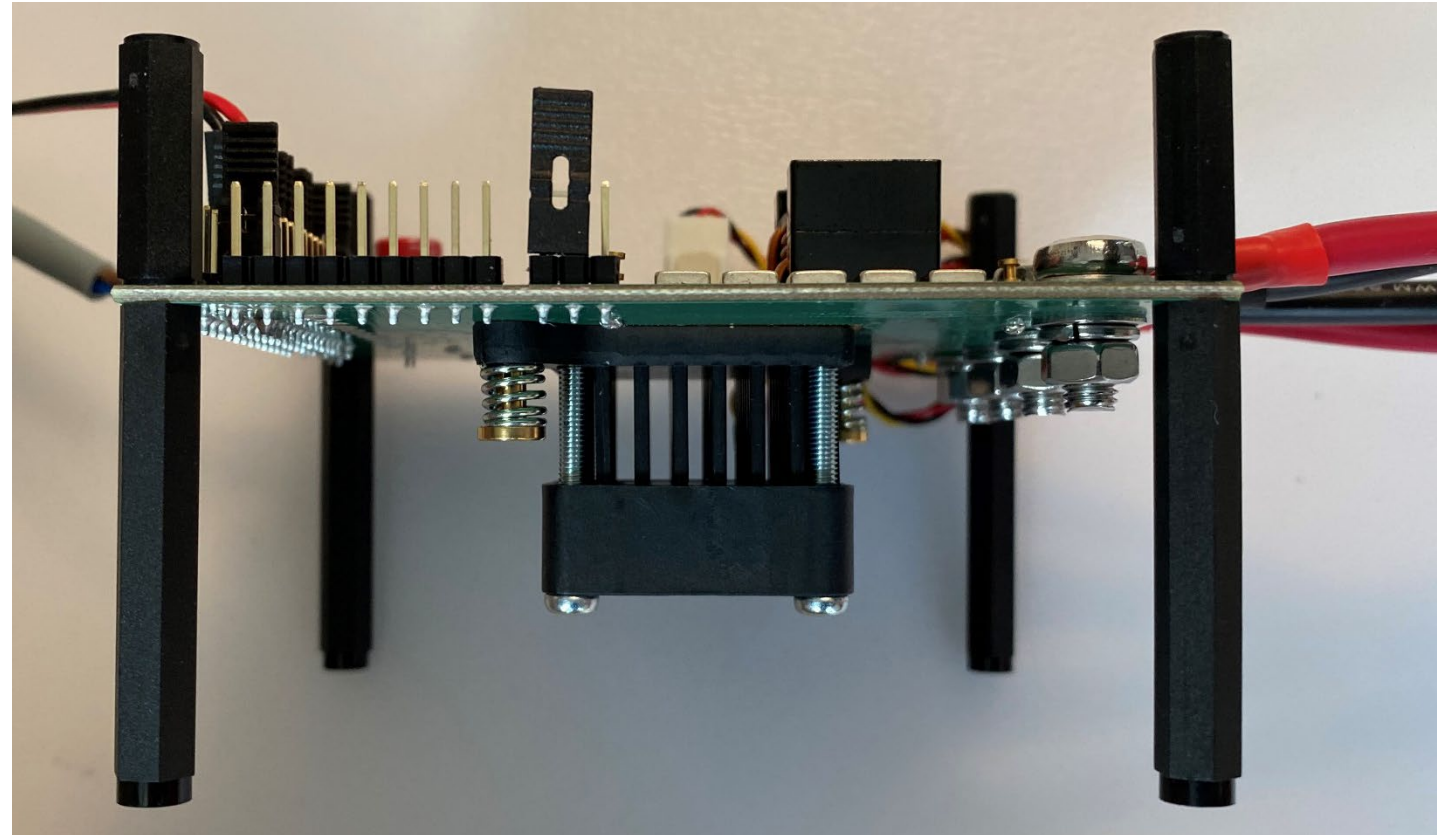


Thermal Performance

Strong thermal management at steady state (with heatsink & fan)

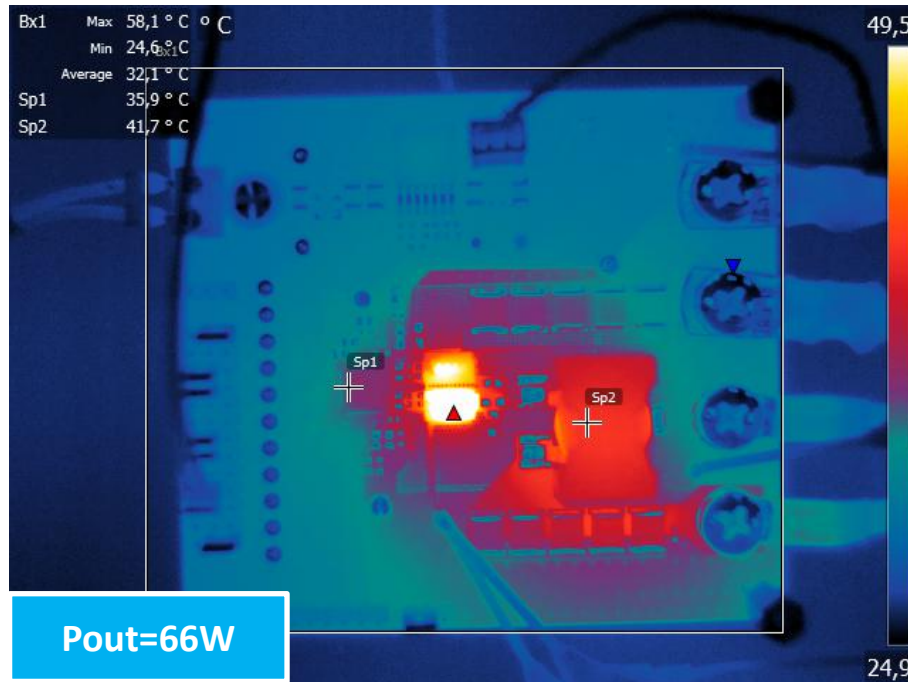
- GaN HEMT on PCB top-side
- Isolating Thermal Interface Material (TIM) on PCB bare copper (ENIG)
- Active pin grid array heatsink on bottom-side of PCB (spring-loaded)

⇒ About 4 K/W from GaN to ambient

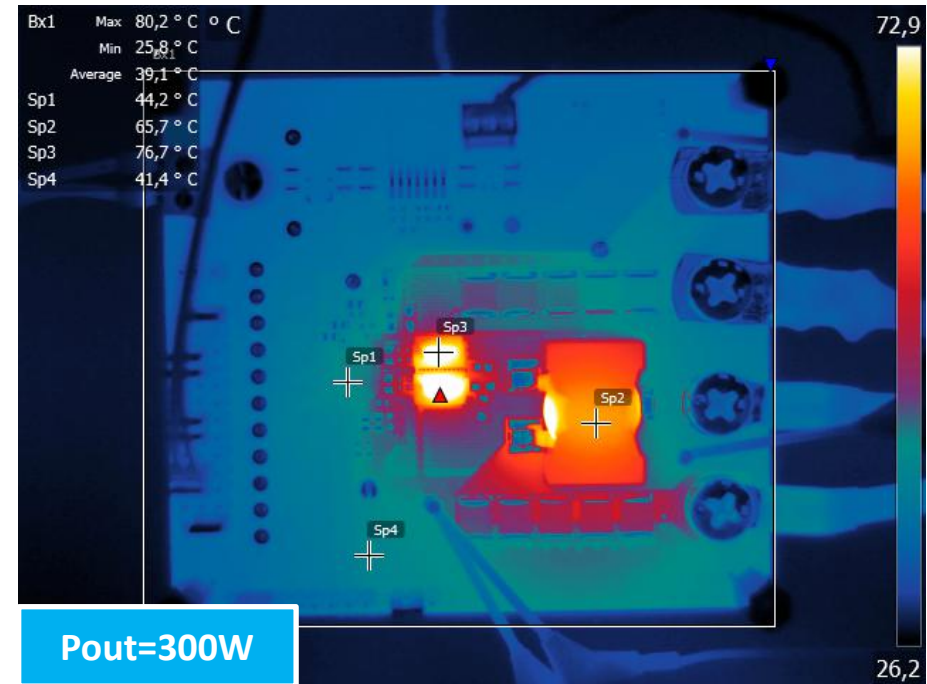


Thermal Performance

Strong thermal management at steady state (with heatsink & fan)



Vin=48V, Vout=3.3V, Iout= 20A, fsw=300kHz
Efficiency = 88.6% Ploss = 8.5W
Max Temp (LS HEMT) = 58.1°C



Vin=48V, Vout=12V, Iout= 25A, fsw=300kHz
Efficiency = 94.5% Ploss = 17.5W
Max temp (LS HEMT) = 80.2°C

Optimized deadtime and PCB layout with a heatsink & fan provides ideal performance

Conclusions

- Improper GaN gate-driving induces many problems, potentially offsetting the benefits of GaN
- Gate-drive can enable the true benefits of GaN:
 - transient speed
 - Low losses
 - High power density
- State-of-the-art solution presented as the MDC901 gate-driver
- Enables a range of enhanced applications:
 - DC/DC converters, LIDAR drivers, class-D audio, BLDC Motor drivers and more
- GaN HEMTs are not the cheapest components, in order to utilize the benefit to the maximal -> [Get Your Gate DRIVE\(R\) Right!](#)

What can we do for you?

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